

## **BigTwin SuperServer SYS-622BT-HNC8R**

2U 4-Node BigTwin with 3 hot-swap 3.5" NVMe/SAS/SATA drives per node



## **Key Applications**

Hyperconverged Infrastructure, Scale-Out File Storage, Back-up & Recovery,

## **Key Features**

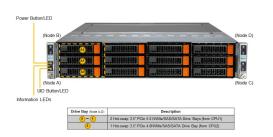
- Dual Socket E2 Intel® Xeon® 6 6700 processors with E-cores up to 165W with air cooling or 330W with liquid cooling
   Single CPU configurations supported while maintaining all expansion slot functionality;
- Up to 16 DIMMs supporting up to 4TB DDR5-6400 in 1DPC;
- Flexible networking with OCP 3.0 AIOM slot;
- Up to 2 PCIe 5.0 x16 LP slots; Tool-less support Internal PCIe 5.0 for 2x NVMe M.2 support onboard Optional 4x NVMe M.2 support onboard with built-in HW RAID1 via SCC-A2NM2241GH-B1;
- Up to 3 front hot-swap 3.5" NVMe/SAS drive bays Built-in SAS3 Support via Broadcom 3808; IT Mode;
- Four hot-pluggable systems (nodes) in a 2U form factor. Each node supports the following;;

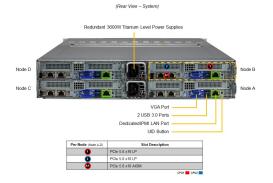


Form Factor	2U Rackmount Enclosure: 449 x 88 x 774mm (17.68" x 3.47" x 30.5")
	Package: 626 x 248 x 1150mm (24.65" x 9.76" x 45.28")
Processor	Dual Socket E2 (LGA-4710)
	Intel® Xeon® 6700 series processors with E-cores
	Up to 144C/144T; Up to 108MB Cache per CPU
System Memory	Slot Count: 16 DIMM slots
	Max Memory (1DPC): Up to 2TB 6400MT/s ECC DDR5 RDIMM
Drive Bays Configuration	Default: Total 3 bays
	• 2 front hot-swap 3.5" PCIe 5.0 NVMe/SAS drive bays
	• 1 front hot-swap 3.5" PCIe 4.0 NVMe/SAS drive bay
	M.2: 2 M.2 PCIe 5.0 x4 NVMe slots (M-key 22110; VROC required for RAID)
Expansion Slots	Default
	• 2 PCIe 5.0 x16 LP slots
	• 1 PCIe 5.0 x16 AIOM slot (OCP 3.0 compatible)
On-Board Devices	SAS: SAS (12Gbps) via Broadcom® 3808; (IT mode)
	Chipset: System on Chip
	Network Connectivity: Via AIOM
Input / Output	LAN: 1 RJ45 1 GbE Dedicated BMC LAN port
	USB: 2 USB 3.0 Type-A ports(Rear)
	Video: 1 VGA port



(Front View - System)





System Cooling	Fans: 4x 14.9K RPM Heavy Duty 80x80x38mm Fan(s) Liquid Cooling: Direct to Chip (D2C) Cold Plate (optional)
Power Supply	2x 3600W Redundant (1 + 1) Titanium Level (96%) power supplies
System BIOS	BIOS Type: AMI 32MB SPI Flash
Management	SuperCloud Composer; Supermicro Server Manager (SSM); Super Diagnostics Offline (SDO); Supermicro Thin-Agent Service (TAS); SuperServer Automation Assistant (SAA) New!
PC Health Monitoring	CPU: Monitors for CPU Cores, Chipset Voltages, Memory  FAN: Fans with tachometer monitoring  Status monitor for speed control  Pulse Width Modulated (PWM) fan connectors  Temperature: Monitoring for CPU and chassis environment  Thermal Control for fan connectors
Dimensions and Weight	Weight: Gross Weight: 96.6 lbs (43.8 kg)  Net Weight: 66.1 lbs (30 kg)  Available Color: Black front & silver body
Operating Environment	Operating Temperature: 10°C ~ 35°C (50°F ~ 95°F)  Non-operating Temperature: -30°C to 60°C (-22°F to 140°F)  Operating Relative Humidity: 8% to 80% (non-condensing)  Non-operating Relative Humidity: 8% to 90% (non-condensing)
Motherboard	Super X14DBT-B
Chassis	CSE-827BQ2-R3K60P